

East of USPB, USP, WPID, JPO

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	55393	histidine or phytic	US-PGPUB; USPAT	OR	ON	2005/11/14 21:39
L2	680557	cmp or \$polish\$ or chemipolish\$ or lap\$ or grind\$ or abrad\$ or slurr\$	US-PGPUB; USPAT	OR	ON	2005/11/14 21:39
L3	368543	silica or "si2o3" or (si with o)	US-PGPUB; USPAT	OR	ON	2005/11/14 21:39
L4	17	1 same 2 same 3	US-PGPUB; USPAT	OR	ON	2005/11/14 21:34
L5	5100	histidine or phytic	JPO; DERWENT	OR	ON	2005/11/14 21:38
L6	423291	cmp or \$polish\$ or chemipolish\$ or lap\$ or grind\$ or abrad\$ or slurr\$	JPO; DERWENT	OR	ON	2005/11/14 21:38
L7	166766	silica or "si2o3" or (si with o)	JPO; DERWENT	OR	ON	2005/11/14 21:38
L8	6	5 and 6 and 7	JPO; DERWENT	OR	ON	2005/11/14 21:38
L9	4625	(histidine or phytic).clm.	US-PGPUB; USPAT	OR	ON	2005/11/14 21:39
L10	102008	(cmp or \$polish\$ or chemipolish\$ or lap\$ or grind\$ or abrad\$ or slurr\$). clm.	US-PGPUB; USPAT	OR	ON	2005/11/14 21:39
L11	59676	(silica or "si2o3" or (si with o)).clm.	US-PGPUB; USPAT	OR	ON	2005/11/14 21:39
L12	17	9 and 10 and 11	US-PGPUB; USPAT	OR	ON	2005/11/14 21:39
L13	13	12 not 4	US-PGPUB; USPAT	OR	ON	2005/11/14 21:39

East 8 USPB USPT, WPID, JPO

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	108904	(hydroxyl or oh).clm.	US-PGPUB; USPAT	OR	OFF	2005/11/14 20:35
L2	524704	"metal oxide" or silica or "si2o3" or abrasive or abressive	US-PGPUB; USPAT	OR	ON	2005/11/14 20:35
L3	99913	("metal oxide" or silica or "si2o3" or abrasive or abressive).clm.	US-PGPUB; USPAT	OR	ON	2005/11/14 19:52
L4	1446	1 with 3	US-PGPUB; USPAT	OR	ON	2005/11/14 19:52
L5	923295	group.clm.	US-PGPUB; USPAT	OR	ON	2005/11/14 19:54
L6	1091	4 with 5	US-PGPUB; USPAT	OR	ON	2005/11/14 19:54
L7	48	4 with (nm or nms or nanometer\$).clm.	US-PGPUB; USPAT	OR	ON	2005/11/14 19:58
L8	39	6 with 7	US-PGPUB; USPAT	OR	ON	2005/11/14 19:54
L9	108335	(cmp or \$polish\$ or chemimech\$ or planariz\$ or lap\$ or grind\$ or abrad\$ or slurry).clm.	US-PGPUB; USPAT	OR	ON	2005/11/14 20:25
L10	5	8 and 9	US-PGPUB; USPAT	OR	ON	2005/11/14 20:02
L11	321	1 with (nm or nms or nanometer\$).clm.	US-PGPUB; USPAT	OR	ON	2005/11/14 20:05
L12	91	3 and 11	US-PGPUB; USPAT	OR	ON	2005/11/14 19:58
L13	6	12 and 9	US-PGPUB; USPAT	OR	ON	2005/11/14 19:58
L14	1	13 not 10	US-PGPUB; USPAT	OR	ON	2005/11/14 19:58
L15	133	6 and 9	US-PGPUB; USPAT	OR	ON	2005/11/14 20:02
L16	128	15 not 13	US-PGPUB; USPAT	OR	ON	2005/11/14 20:03
L17	90	16 and ("hydroxyl group" or "hydroxyl groups" or "oh group" or "oh groups").clm.	US-PGPUB; USPAT	OR	ON	2005/11/14 20:47
L18	4	17 and (nm or nms or nanometer\$).clm.	US-PGPUB; USPAT	OR	ON	2005/11/14 20:07
L19	16	17 and (nm or nms or nanometer\$)	US-PGPUB; USPAT	OR	ON	2005/11/14 20:36
L20	12	19 not 18	US-PGPUB; USPAT	OR	ON	2005/11/14 20:13
L21	401670	mu or mus or micron or microns	US-PGPUB; USPAT	OR	ON	2005/11/14 20:36

L22	30	1 with 21 with 3	US-PGPUB; USPAT	OR	ON	2005/11/14 20:14
L23	6	9 and 22	US-PGPUB; USPAT	OR	ON	2005/11/14 20:15
L24	3	23 not (13 or 18 or 19)	US-PGPUB; USPAT	OR	ON	2005/11/14 20:15
L25	71	17 not (13 or 18 or 19 or 23)	US-PGPUB; USPAT	OR	ON	2005/11/14 20:26
L26	521707	(hydroxyl or oh)	US-PGPUB; USPAT	OR	OFF	2005/11/14 20:25
L27	14535	2 with 26	US-PGPUB; USPAT	OR	OFF	2005/11/14 20:25
L28	5478	27 with group	US-PGPUB; USPAT	OR	ON	2005/11/14 20:25
L29	271	28 same (cmp or \$polish\$ or chemimech\$ or planariz\$ or lap\$ or grind\$ or abrad\$ or slurry)	US-PGPUB; USPAT	OR	ON	2005/11/14 20:35
L30	17	29 same (nm or nms or nanometer\$)	US-PGPUB; USPAT	OR	ON	2005/11/14 20:26
L31	13	30 not (13 or 18 or 19 or 23 or 17)	US-PGPUB; USPAT	OR	ON	2005/11/14 20:28
L32	10680	26 same (nm or nms or nanometer\$)	US-PGPUB; USPAT	OR	ON	2005/11/14 20:27
L33	1737	32 same 2	US-PGPUB; USPAT	OR	ON	2005/11/14 20:27
L34	111	33 same (cmp or \$polish\$ or chemimech\$ or planariz\$ or lap\$ or grind\$ or abrad\$ or slurry)	US-PGPUB; USPAT	OR	ON	2005/11/14 20:28
L35	93	34 not (13 or 18 or 19 or 23 or 17 or 30)	US-PGPUB; USPAT	OR	ON	2005/11/14 20:28
L36	277389	"metal oxide" or silica or "si2o3" or abrasive or abressive	JPO; DERWENT	OR	ON	2005/11/14 20:35
L37	297505	(hydroxyl or oh)	JPO; DERWENT	OR	OFF	2005/11/14 20:35
L38	427224	(cmp or \$polish\$ or chemimech\$ or planariz\$ or lap\$ or grind\$ or abrad\$ or slurry)	JPO; DERWENT	OR	ON	2005/11/14 20:36
L39	96790	(nm or nms or nanometer\$)	JPO; DERWENT	OR	ON	2005/11/14 20:36
L40	271224	mu or mus or micron or microns	JPO; DERWENT	OR	ON	2005/11/14 20:36
L41	89	36 and 37 and 38 and (39 or 40)	JPO; DERWENT	OR	ON	2005/11/14 20:48
L42	2455	37 with (39 or 40)	JPO; DERWENT	OR	ON	2005/11/14 20:37

L43	35	41 and 42	JPO; DERWENT	OR	ON	2005/11/14 20:40
L44	54	41 not 43	JPO; DERWENT	OR	ON	2005/11/14 20:40
L45	68843	"hydroxyl group" or "hydroxyl groups" or "oh group" or "oh groups"	JPO; DERWENT	OR	ON	2005/11/14 20:47
L46	598	36 and 37 and 38	JPO; DERWENT	OR	ON	2005/11/14 20:48
L47	544	46 not 44	JPO; DERWENT	OR	ON	2005/11/14 20:48
L48	126	45 and 47	JPO; DERWENT	OR	ON	2005/11/14 20:48

STN 8 Caplus Japio, USPAT2

(FILE 'HOME' ENTERED AT 18:06:22 ON 14 NOV 2005)

FILE 'REGISTRY' ENTERED AT 18:06:29 ON 14 NOV 2005

L1 1 S PHYTIC ACID/CN
L2 7148 S SILICA

FILE 'CAPLUS' ENTERED AT 18:07:15 ON 14 NOV 2005

L3 213081 S CMP OR ?POLISH? OR CHEMIMECH? OR LAP? OR GRIND? OR ABRAD? OR
L4 4 S (PHYTIC OR L1) AND L3 AND (SI2O3 OR SILICA OR L2)
L5 71 S L3 AND (L1 OR PHYTIC)
L6 0 S L5 AND (TA OR TANTALUM OR TAN)
L7 0 S L5 AND (SI(10W)O)
L8 57 S (L1 OR PHYTIC) AND SLURR?
L9 54 S L8 NOT L5
L10 3 S L9 AND (SI2O3 OR SILICA? OR L2 OR (SI(10W)O))

FILE 'JAPIO' ENTERED AT 18:10:38 ON 14 NOV 2005

L11 1 S L8
L12 0 S L4
L13 0 S USPAT2

FILE 'USPAT2' ENTERED AT 18:11:12 ON 14 NOV 2005

L14 104 S (L1 OR PHYTIC) AND L3
L15 85 S L14 AND (L2 OR SILICA? OR SI2O3 OR SI(5W)O)
L16 65 S (L1 OR PHYTIC) AND SLURR? AND (L2 OR SILICA? OR SI2O3 OR SI(5
L17 96 S L15 OR L6
L18 3 S (L1 OR PHYTIC) (P) (L3 OR SLURR?)
L19 96 S L17 NOT L18
L20 8 S L19 AND (SEMICONDUCT? OR WAFER? OR CHIP?)